

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	16638	@ad<="20020524" and ('contact pad' or 'bond pad' or bonding pad or 'land pad') with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 09:13
L4	592	@ad<="20020524" and ('contact pad' or 'bond pad' or bonding pad or 'land pad') with 'gold' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 09:16
L5	845	@ad<="20020524" and ('contact pad' or 'bond pad' or bonding pad or 'land pad') with 'gold' same 'polyimide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 09:16
L6	252	@ad<="20020524" and ('contact pad' or 'bond pad' or bonding pad or 'land pad') with 'gold' with 'polyimide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 09:16
L8	1	"5235212".PN.	USPAT; USOCR	OR	ON	2005/10/26 10:00
L9	1	"5060050".PN.	USPAT; USOCR	OR	ON	2005/10/26 10:00
S1	3	((("6620728") or ("6383916"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 15:43
S2	1	"5818110".PN.	USPAT	OR	OFF	2003/10/08 11:19
S3	1	"5827776".PN.	USPAT	OR	OFF	2003/10/08 11:19
S4	1	"5827778".PN.	USPAT	OR	OFF	2003/10/08 11:20
S5	1	"5910020".PN.	USPAT	OR	OFF	2003/10/08 11:20
S6	1	"5953626".PN.	USPAT	OR	OFF	2003/10/08 11:20
S7	1	"6100548".PN.	USPAT	OR	OFF	2003/10/08 11:20
S8	1	"6130457".PN.	USPAT	OR	OFF	2003/10/08 11:20
S9	259	@ad<="19981221" and 'interconnection' and 'multilayered' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:40
S10	63	@ad<="19981221" and 'devices' same 'interconnecting' same 'metallization' same 'structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/08 12:01

S11	6	((("6489647") or ("6303423") or ("6455885")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/08 11:51
S12	11	((("5212403") or ("55010063") or ("5055907") or ("5106461") or ("5635767") or ("5686764")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/08 12:02
S13	257	@ad<="19981221" and 'interconnection' and 'multi' adj1 'level' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/08 13:17
S14	672	@ad<="19981221" and (438/637). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:54
S15	174	@ad<="19981221" and (438/638). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:46
S16	1149	@ad<="19981221" and (438/622). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:54
S17	2230	@ad<="19981221" and (438/624). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:54
S18	217	@ad<="19981221" and (438/626). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S19	365	@ad<="19981221" and (438/631). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S20	286	@ad<="19981221" and (438/633). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S21	254	@ad<="19981221" and (438/639). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55

S22	1	"6130457".PN.	USPAT	OR	OFF	2003/10/08 13:48
S23	1	"6100548".PN.	USPAT	OR	OFF	2003/10/08 13:48
S24	1	"5953626".PN.	USPAT	OR	OFF	2003/10/08 13:48
S25	1	"5953626".PN.	USPAT	OR	OFF	2003/10/08 13:48
S26	1	"5910020".PN.	USPAT	OR	OFF	2003/10/08 13:49
S27	1	"5827778".PN.	USPAT	OR	OFF	2003/10/08 13:49
S28	1	"5827776".PN.	USPAT	OR	OFF	2003/10/08 13:49
S29	1	"5818110".PN.	USPAT	OR	OFF	2003/10/08 13:49
S30	1	"5686764".PN.	USPAT	OR	OFF	2003/10/08 13:49
S31	1	"5635767".PN.	USPAT	OR	OFF	2003/10/08 13:49
S32	1	"5501006".PN.	USPAT	OR	OFF	2003/10/08 13:50
S33	1	"5106461".PN.	USPAT	OR	OFF	2003/10/08 13:50
S34	1	"5055907".PN.	USPAT	OR	OFF	2003/10/08 13:50
S35	1	"5818110".PN.	USPAT	OR	OFF	2003/10/08 13:51
S36	1	"5827776".PN.	USPAT	OR	OFF	2003/10/08 13:51
S37	1	"5827778".PN.	USPAT	OR	OFF	2003/10/08 13:51
S38	1	"5055907".PN.	USPAT	OR	OFF	2003/10/08 13:51
S39	1	"5106461".PN.	USPAT	OR	OFF	2003/10/08 13:51
S40	1	"5212403".PN.	USPAT	OR	OFF	2003/10/08 13:52
S41	1	"5372967".PN.	USPAT	OR	OFF	2003/10/08 13:52
S42	1	"5635767".PN.	USPAT	OR	OFF	2003/10/08 13:52
S43	1	"5686764".PN.	USPAT	OR	OFF	2003/10/08 13:52
S44	1	"6376895".PN.	USPAT	OR	OFF	2003/10/08 13:52
S45	1	"6008102".PN.	USPAT	OR	OFF	2003/10/08 13:53
S46	1	"5884990".PN.	USPAT	OR	OFF	2003/10/08 13:53
S47	1	"5686764".PN.	USPAT	OR	OFF	2003/10/08 13:53
S48	1	"5635767".PN.	USPAT	OR	OFF	2003/10/08 13:53
S49	1	"5576680".PN.	USPAT	OR	OFF	2003/10/08 13:53
S50	1	"5501006".PN.	USPAT	OR	OFF	2003/10/08 13:54
S51	1	"5372967".PN.	USPAT	OR	OFF	2003/10/08 13:54
S52	1	"5212403".PN.	USPAT	OR	OFF	2003/10/08 13:54
S53	1	"6040226".PN.	USPAT	OR	OFF	2003/10/08 13:54
S54	1	"6008102".PN.	USPAT	OR	OFF	2003/10/08 13:55
S55	2	("5083187").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/03 14:06
S56	3	@ad<="19981221" and 'interconnection' and 'multilayered' with 'metal' and 'hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:41

S57	163	@ad<="19981221" and 'contact hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:14
S58	32	@ad<="19981221" and 'interconnection' and 'contact hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:41
S59	218	@ad<="19981221" and 'interconnection' and 'hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/03 14:52
S60	38	@ad<="19981221" and 'interconnection' and 'through hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:31
S61	592	@ay<="2002" and 'interconnecting' same 'integrated circuits' and 'via' and ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:11
S62	10	@ay<="2002" and 'interconnecting' with 'integrated circuits' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:20
S63	127	@ad<="19981221" and 'interconnection' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:32
S64	251	@ay<="2002" and 'interconnection' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:08
S65	337	@ay<="2002" and 'polyimide' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:36
S66	54	@ay<="2002" and 'polyimide' same 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:43
S67	14	@ay<="2002" and 'interconnection' and 'polyimide' same 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:43

S68	176	@ad<="19981221" and (438/638). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:14
S69	1150	@ad<="19981221" and (438/622). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:13
S70	2231	@ad<="19981221" and (438/624). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:47
S71	218	@ad<="19981221" and (438/626). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:47
S72	366	@ad<="19981221" and (438/631). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:47
S73	287	@ad<="19981221" and (438/633). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 08:48
S74	255	@ad<="19981221" and (438/639). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:15
S75	211	@ad<="19981221" and (257/759). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:38
S76	1372	@ad<="19981221" and (257/758). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:14
S77	236	@ad<="19981221" and (438/623). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:14
S78	471	@ad<="19981221" and (438/118). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:14

S79	414	@ad<="19981221" and (438/652). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:15
S80	670	@ad<="19981221" and (257/750). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 16:25
S81	3	@ay<="2002" and (257/759).ccls. and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 09:41
S82	80	@ay<="2002" and 'wiring layers' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S83	2	("6620728").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/07 10:31
S84	160	@ay<="2002" and 'interconnecting' same 'integrated circuits' same 'via' and ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:42
S85	32	@ad<="19981221" and 'interconnection' and 'contact hole' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:14
S86	62	@ad<="19981221" and 'integrated circuits' and 'contact hole' with ""0. 1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:32
S87	0	@ad<="19981221" and 'contact hole' with ""0.1"" same 'adhesion' same 'seed'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:32
S88	1	@ay<="2002" and 'contact hole' with ""0.1"" same 'adhesion' same 'seed'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:33
S89	7	@ay<="2002" and 'contact hole' with ""0.1"" and 'adhesion' and 'seed'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:33

S90	14	@ay<="2002" and 'contact hole' with ""0.1"" and 'barrier' and 'seed'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/07 11:33
S91	1154	@ad<="19981221" and (438/622). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:54
S92	2232	@ad<="19981221" and (438/624). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S93	220	@ad<="19981221" and (438/626). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S94	367	@ad<="19981221" and (438/631). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S95	288	@ad<="19981221" and (438/633). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S96	255	@ad<="19981221" and (438/639). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S97	82	@ay<="2002" and 'wiring layers' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 11:55
S98	90	@ad<="20020524" and 'device' and 'interconnection' and 'pad' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:02
S99	186	@ay<="20020524" and 'interconnecting' same 'integrated circuits' same 'via' and ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:47
S10 0	9	@ad<="20020524" and 'device' and 'interconnection' and 'bonding pad' and 'via' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:51

S10 1	174	@ay<="20020524" and 'device' and 'interconnecting' same 'integrated circuits' same 'via' and ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 13:47
S10 2	0	@ad<="20020524" and 'device' and 'interconnection' and 'damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:06
S10 3	3	@ad<="20020524" and 'device' and 'copper interconnection' and 'damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:05
S10 4	3	@ad<="20020524" and 'copper interconnection' and 'damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:05
S10 5	14	@ad<="20020524" and 'device' and 'interconnection' and 'damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:11
S10 6	14	@ad<="20020524" and 'interconnection' and 'damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:24
S10 7	8	((("6683381") or ("6475912") or ("6271119") or ("6187673"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/04 14:12
S10 8	19	@ad<="20020524" and 'dual damascene' and 'pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 14:41
S10 9	1	@ad<="20020524" and 'dual damascene' and 'bond pad' and 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 15:07
S11 0	3	@ad<="20020524" and 'dual damascene' same 'diameter' with ""0.1""	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 08:51
S11 1	10	((("6683381") or ("6475912") or ("6271119") or ("6187673") or ("6762115"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 15:44

S11 2	56	@ad<="20020524" and 'IC' and 'dual damascene' and 'metallization structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 13:29
S11 3	1	@ad<="20020524" and 'IC' and 'dual damascene' with 'diameter' and 'metallization structure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 08:53
S11 4	7	@ad<="20020524" and 'IC interconnection' and 'dual damascene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:19
S11 5	2	"20010000416"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:07
S11 6	21	"6376353"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:08
S11 7	15	((("6376353") or ("6333559") or ("6204165") or ("6298551") or ("6627994") or ("6664135") or ("6828224"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 09:09
S11 8	5	@ad<="20020524" and 'interconnection' and 'BSG' and 'BCB' and 'damascene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:23
S11 9	1	@ad<="20020524" and 'IC' and 'interconnecting wiring' and 'BSG' and 'BCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:24
S12 0	48	'Megic Corporation' and 'interconnecting'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:24
S12 1	3	@ad<="20020524" and 'IC' and 'interconnection' and 'metallization' and 'BSG' and 'BCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:36
S12 2	11	@ad<="20020524" and 'interconnecting metallization' and 'BCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:37

S12 3	12	@ad<="20020524" and 'device' and 'IC interconnection' and 'BCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:40
S12 4	23	@ad<="20020524" and 'high power' and 'IC interconnection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:40
S12 5	42	@ad<="20020524" and 'IC' and 'damascene' and 'wire' and 'IMD'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:49
S12 6	29	@ad<="20020524" and 'semiconductor substrate' and ('IC' or 'device') and 'wire bonding' and 'IMD'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:50
S12 7	276	@ad<="20020524" and 'semiconductor substrate' and 'top' with 'metallization' and 'wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:57
S12 8	7	@ad<="20020524" and 'semiconductor substrate' and 'top' with 'metal' and 'wire' and 'TiN' and 'copper' and 'BSG'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:54
S12 9	310	@ad<="20020524" and 'semiconductor substrate' and 'top' with 'metal' and 'wire' and 'TiN' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:54
S13 0	694	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'top' with 'metal' and 'wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 09:58
S13 1	50	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'top' with 'metal' and 'wire' and 'barrier' and 'seed' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 10:40
S13 2	24	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'metal wire' and 'barrier' and 'seed' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 10:56
S13 3	9	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'metal wire' and 'interconnection' and 'barrier' and 'seed' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:19

S13 4	8	@ad<="20020524" and 'chip structure' same 'resistance capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:24
S13 5	0	@ad<="20020524" and 'metal wire structure' same 'resistance capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:24
S13 6	1	@ad<="20020524" and 'wire structure' same 'resistance capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:26
S13 7	8	@ad<="20020524" and 'interconnect structure' same 'resistance capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 12:17
S13 8	8	@ad<="20020524" and 'interconnect structure' same 'capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:26
S13 9	63	@ad<="20020524" and 'interconnect structure' same 'RC delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:30
S14 0	31	@ad<="20020524" and 'semiconductor substrate' with ('device' or 'IC') and 'interconnect structure' same 'RC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:43
S14 1	0	@ad<="20020524" and 'semiconductor substrate' with 'IC' and 'thick bonding pad' and 'metal wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:44
S14 2	31	@ad<="20020524" and 'semiconductor substrate' with 'IC' and 'bonding pad' and 'metal wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:44
S14 3	138	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'bonding pad' and 'metal wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:55
S14 4	1	"5701666".PN.	USPAT; USOCR	OR	ON	2005/04/20 11:48
S14 5	1	"6306749".PN.	USPAT; USOCR	OR	ON	2005/04/20 11:48
S14 6	1	"6303423".PN.	USPAT; USOCR	OR	ON	2005/04/20 11:49

S14 7	5	@ad<="20020524" and 'semiconductor substrate' with 'device' and 'bonding pad' and 'metal wire' and 'top metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 11:55
S14 8	13	@ad<="20020524" and 'chip structure' and 'capacitance delay'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 12:27
S14 9	12	((("6762115") or ("5612254") or ("5534465") or ("6596560") or ("6303423") or ("6495442")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:28
S15 0	2	("6798073").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 13:26
S15 1	1	@ad<="20020524" and 'damascene' and 'sputtering' with 'adhesive' and 'electroplating' with 'seed' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:01
S15 2	19	@ad<="20020524" and 'damascene' and 'sputtering' with 'Ti' and 'electroplating' with 'seed' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:48
S15 3	0	@ad<="20020524" and 'damascene' and 'polymer' with 'cure' with 'Ti' and 'electroplating' with 'seed' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:48
S15 4	4	@ad<="20020524" and 'damascene' and 'polymer' with 'cure' and 'electroplating' with 'seed' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:48
S15 5	2	@ad<="20020524" and 'damascene' and 'BCB' with 'cure' and 'electroplating' with 'seed' with 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:58
S15 6	1	@ad<="20020524" and 'damascene' and 'BCB' with 'cure' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 14:59
S15 7	0	@ad<="20020524" and 'damascene' and 'polymer' with 'cure' same 'reduced thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 15:00

S15 8	1	@ad<="20020524" and 'damascene' and 'polymer' with 'cure' same 'after' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 15:01
S15 9	17	@ad<="20020524" and 'damascene' and 'polymer' same 'cured' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 15:04
S16 0	15	@ad<="20020524" and 'damascene' and 'polymer' same 'thickness' same 'after curing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:05
S16 1	4	@ad<="20020524" and 'damascene' and 'copper' with 'cap' with 'nickel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:37
S16 2	0	@ad<="20020524" and 'copper plug' with 'cap' with 'nickel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:34
S16 3	301	@ad<="20020524" and 'copper' with 'cap' with 'nickel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:35
S16 4	2	@ad<="20020524" and 'interconnection' same 'copper' with 'cap' with 'nickel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:36
S16 5	37	@ad<="20020524" and 'contact' same 'copper' with 'cap' with 'nickel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:36
S16 6	242	@ad<="20020524" and 'damascene' and 'copper' with 'cap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:37
S16 7	96	@ad<="20020524" and 'damascene' same 'copper' with 'cap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:38
S16 8	0	@ad<="20020524" and 'cap' with 'nickel' same 'damascene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/20 16:38

S16 9	7	@ad<="20020524" and 'cap' with 'nickel' and 'damascene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:29
S17 0	2	"20040166659"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 14:52
S17 1	651	@ad<="20020524" and 'substrate' and 'device' and 'damascene' and 'gold' and 'metallization'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:30
S17 2	372	@ad<="20020524" and 'substrate' and 'device' and 'damascene' and 'gold' and 'metallization' and 'interconnection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:31
S17 3	10	@ad<="20020524" and 'substrate' and 'device' and 'damascene' and 'gold' and 'interconnecting metallization'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:34
S17 4	9	@ad<="20020524" and 'substrate' and 'device' and 'gold' same 'interconnecting metallization'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:36
S17 5	52	@ad<="20020524" and 'substrate' and 'device' and 'gold' and 'interconnecting metallization'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:36
S17 6	193	@ad<="19981221" and 'interconnection' and 'multilayered' and 'metal' with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:42
S17 7	67	@ad<="19981221" and 'interconnection' same 'dielectric' with 'nitride' and 'metal' with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:44
S17 8	65	@ad<="19981221" and 'device' and 'interconnection' same 'dielectric' with 'nitride' and 'metal' with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:55
S17 9	151	'lin' and 'megic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 15:56
S18 0	1	"6303423".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:09

S18 1	1	"6180426".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:09
S18 2	1	"6130457".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:09
S18 3	1	"6100548".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:09
S18 4	1	"5953626".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:09
S18 5	1	"5910020".PN.	USPAT; USOCR	OR	ON	2005/06/24 16:10
S18 6	164	@ad<="20020524" and 'advanced micro devices' and 'wollesen'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 10:52
S18 7	4	(("6620728") or ("6383916")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/28 09:27
S18 8	40	@ad<="20020524" and 'interconnecting line' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 10:53
S19 0	15	@ad<="20020524" and 'contacting pad' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 11:20
S19 1	1002	@ad<="20020524" and 'bonding pad' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 11:20
S19 2	193	@ad<="20020524" and 'bonding pad' with 'thickness' and 'interconnection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 11:30
S19 3	568	@ad<="20020524" and 'thick' with 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 16:30
S19 4	64	@ad<="20020524" and 'thick' with 'bonding pad' and 'interconnecting'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 11:40
S19 5	161	@ad<="20020524" and 'bonding pad' same 'thickness' with 'micron'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 11:40

S19 6	2142	@ad<="20022405" and (257/750-751).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 16:25
S19 7	1958	@ad<="20022405" and (257/774). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 16:25
S19 8	372	@ad<="20022405" and (257/771). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 16:26
S19 9	845	@ad<="20022405" and (257/762). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/28 16:28
S20 0	7	((("6555459") or ("6583043") or ("6762115")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:27
S20 1	1	"6596560".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 2	1	"6495442".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 3	1	"6383916".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 4	1	"6303423".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 5	1	"5612254".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 6	1	"5534465".PN.	USPAT; USOCR	OR	ON	2005/10/25 16:29
S20 7	100	@ad<="20020524" and 'thick' with 'bonding pad' same 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:04
S20 8	2	"20020038903"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 16:46
S20 9	2	"20020084516"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 16:47

S21 0	5	((("6204165") or ("6016000")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 16:48
S21 1	2	"20010000416"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 16:48
S21 2	1990	@ad<="20020524" and 'gold' with 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:06
S21 3	8	@ad<="20020524" and 'gold' with 'bonding pad' and 'silicon substrate' and 'electroplate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:14
S21 4	1	"5018256".PN.	USPAT; USOCR	OR	ON	2005/10/25 17:14
S21 5	22	@ad<="20020524" and 'gold' with 'bonding pad' and 'electroplate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:17
S21 6	37	@ad<="20020524" and 'gold' with 'contact pad' and 'electroplate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:28
S21 7	4	((("6274935") or ("6833604")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/25 17:23
S21 8	1	"5385661".PN.	USPAT; USOCR	OR	ON	2005/10/25 17:27
S21 9	1	"5320689".PN.	USPAT; USOCR	OR	ON	2005/10/25 17:27
S22 0	1	"5308796".PN.	USPAT; USOCR	OR	ON	2005/10/25 17:27
S22 1	599	@ad<="20020524" and ('contact pad' or 'bond pad' or 'bonding pad') and ('electroplate' or 'electroplating') with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:29
S22 2	369	@ad<="20020524" and 'thick' and ('contact pad' or 'bond pad' or 'bonding pad') and ('electroplate' or 'electroplating') with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 17:29